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102640648
PATENTS ONLY

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Byung-Jae LEE

12.24.03

2. Name and address of receiving party(ies):
Name: Hynix Semiconductor Inc.

Additional name(s) of conveying party(ies) attached?
☒ No ☐ Yes

Internal Address: _____
Street Address: San 136-1, Ami-ri, Bubal-eub,
Ichon-shi

3. Nature of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

City: Kyungki-do State: _____ ZIP: 467-8
60

Execution Date: 12/19/03

Additional name(s) & address(es) attached? ☒ No ☐ Yes

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 12/19/03

A. Patent Application No.(s)

10746523

B. Patent No.(s)

Additional numbers attached? ☒ No ☐ Yes

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Blakely, Sokoloff, Taylor & Zafman LLP

Internal Address: _____

Street Address: 12400 Wilshire Boulevard
7th Floor

City: Los Angeles State: CA ZIP: 90025

6. Total number of applications and patents involved: 1

7. Total Fee (37 CFR 3.41).....\$ 40.00

☒ Enclosed
☐ Authorized to be charged to deposit account

8. Deposit Account Number:

02-2666

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.

Eric S. Hyman

Name of Person Signing

Eric S. Hyman
Signature

December 24, 2003

Date

Total number of pages including cover sheet, attachments, and document: 2

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Mail documents to be recorded with required cover sheet information to:

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P.O. Box 1450
Alexandria, VA 22313-1450

Docket No. 51876P527

PATENT
REEL: 014850 FRAME: 0006

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned,

LEE, BYUNG-JAE

Hereby sells, assigns, and transfers to:

Hynix Semiconductor Inc.

a corporation of Republic of Korea, having a principal place of business at:

San 136-1, Ami-ri, Bubal-eub, Ichon-shi, Kyoungki-do, 467-860, Republic of Korea ("Assignee"), and its successors, assigns and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent,

[xx] which has been executed by the undersigned concurrently herewith,

 which was filed and assigned Serial No.

and is entitled:

SEMICONDUCTOR MEMORY DEVICE WITH ENHANCED REPAIR EFFICIENCY

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: December 19, 2003

Lee Byung Jae
Name: LEE, BYUNG-JAE

Date: , 2003

Name: